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GP 2822

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Haruo Hyodo et al.

Art Unit : 2822

Serial No. : 09/963,267

Examiner : Ida W. Soward

Filed : September 26, 2001

Title : SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

S/A Amdt
9/26/02
AWall

Commissioner for Patents
Washington, D.C. 20231

RESPONSE

In response to the action mailed February 19, 2002, please amend the application as follows:

In the claims:

Please amend claim 1 as follows:

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Sub C1
A1
-- 1. (Amended) A semiconductor device comprising:
a supporting substrate made of insulating material;
a conductive pattern provided on a surface of the supporting substrate;
an external connecting terminal provided on a back surface of the supporting substrate
and electrically connected to the conductive pattern;
a circuit element provided on the conductive pattern;
a glass plate that covers the circuit element and that forms a hollow airtight portion
between the supporting substrate and the glass plate; and
an adhesive resin applied over an entire surface of the glass plate. --

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Please add claims 8 to 11.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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